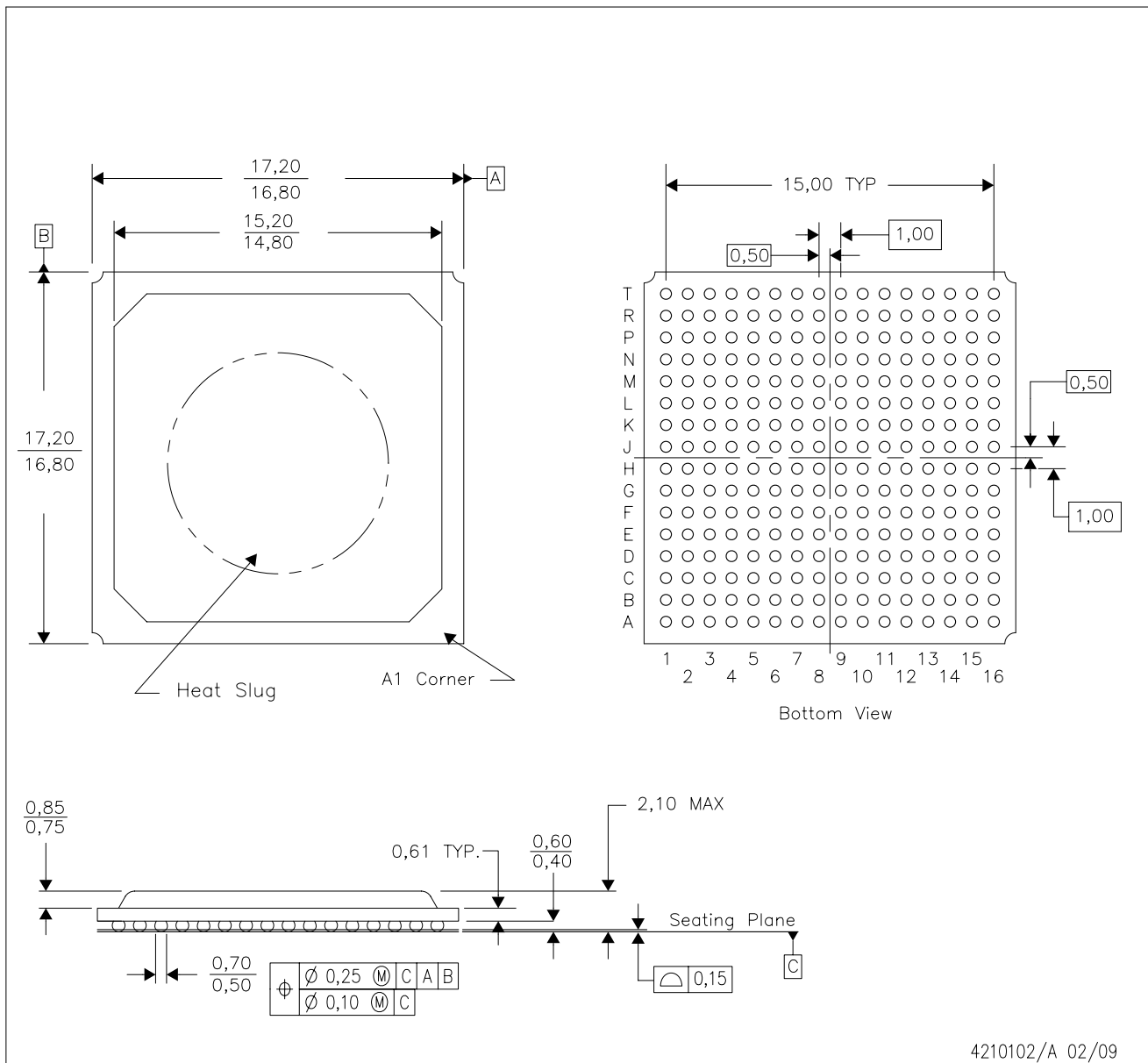


ZET (S-PBGA-N256)

PLASTIC BALL GRID ARRAY



4210102/A 02/09

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Thermally Improved BGA with heat slug (TI-BGA with HSL).
 - D. This is a Pb-free solder ball design.

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